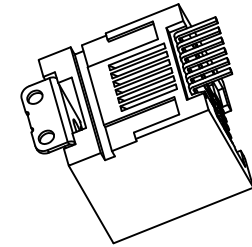
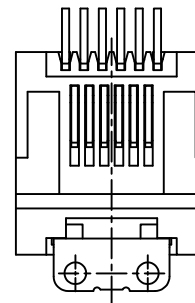
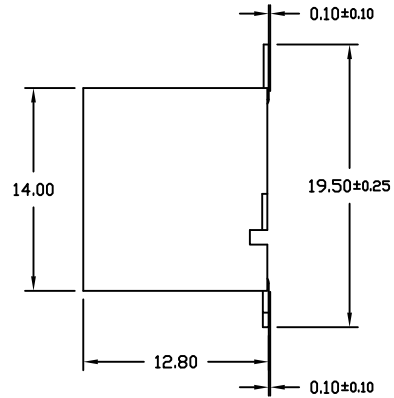
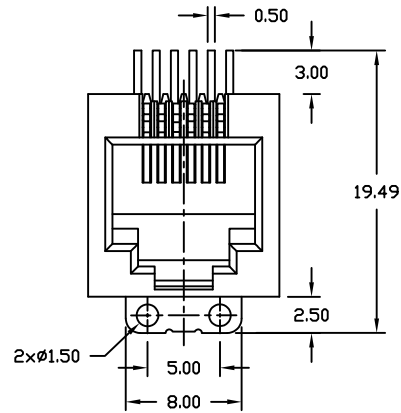
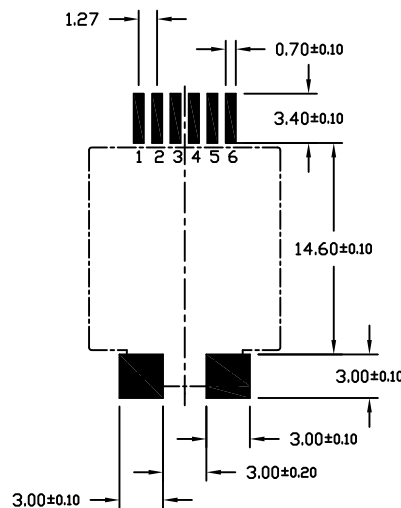
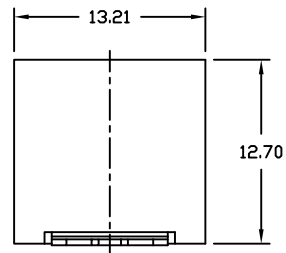
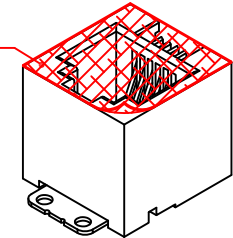


REV.	DESCRIPTION	DATE	DRAWN
A	RoHS	13.07.2006	Ronny
B	P/N: -TSA03- -> -T1S0-	23.02.2009	Ronny
C	add pickup tape; PN add /R	26.11.2010	Ronny
D	update description	13.02.2011	Ronny
E	New DWG. No.	01.02.2012	Ronny



PickUp tape



NOTE :

- MATERIAL: HI TEMP THERMOPLASTIC UL94V-0
STANDARD COLOR-BLACK
CONTACT-PHOSPHOR BRONZE; 0.35mm THICK
SELECTIVE GOLD/TIN PLATED OVER Ni
HOLD DOWN: COPPER ALLOY; 0.40mm THICK
TIN OVER NICKEL
- ENVIRONMENTAL:
OPERATING TEMPERATURE: -20°C TO +85°C
PROCESSING TEMPERATURE:
+230°C FOR 60 SEC. max.
+260°C -5/+0 FOR 5 SEC max.
- ELECTRICAL:
CURRENT RATING: 1.5A max. (@25°C)
VOLTAGE RATING: 150V AC max.
CONTACT RESISTANCE: 15mΩ max.
DIELECTRIC WITHSTANDING VOLTAGE:
1000V rms 1 MINUTE (60Hz)
INSULATION RESISTANCE:
500MΩ min.
- CAVITY CONFIRMS TO FCC RULES AND
REGISTRATION PAR68, SUBPARTS F.
- PACKING: REEL

PART NUMBER	GOLD PLATING CONTACT AREA
MJT-166-T1S0-96/R	6μ"
MJT-166-T1S0-97/R	15μ"
MJT-166-T1S0-98/R	30μ"
MJT-166-T1S0-9H/R	50μ"

RECOMMENDED PCB LAYOUT



UNIT	mm	GENERAL TOLERANCE		DRAWN	DATE	DWG. NO.	SHEET 1/1
SCALE	Free	X.° ±	X. ±	Ronny	13.07.2006	1811300	REV. E
		.X° ±	.X ±	CHECK	DATE	SERIES NO.	
		.XX° ±	.XX ±	Ronny	01.02.2012	MJT-166-T1S0-xx/R	
		ANG ± 0,5°	.XXX ±	APPROVE	DATE		
				Hogi	01.02.2012		

SMT PCB Jack RJ12 <6P6C>
Top Entry
NON Shielded

REV.	DESCRIPTION	DATE	DRAWN
A	New	13.08.2001	RH
C	Frame	02.03.2009	Ronny
D	change housing & P/N: -9x -> -7x/R	16.06.2009	Ronny
E	New DWG. No.	01.02.2016	Ronny
F	PN -T3AM0- -> -W3S0- DIM 16,20-> 15,90; 0,43 -> 0,80	01.07.2016	Ronny



Specifications

Electrical

Current rating: 1.5A max. (@25°C)
 Insulation resistance: 500MΩ min.
 Contact resistance: 15mΩ max.
 Voltage rating: 150V AC max.
 Withstanding voltage: 1000V AC rms 60Hz / Minute

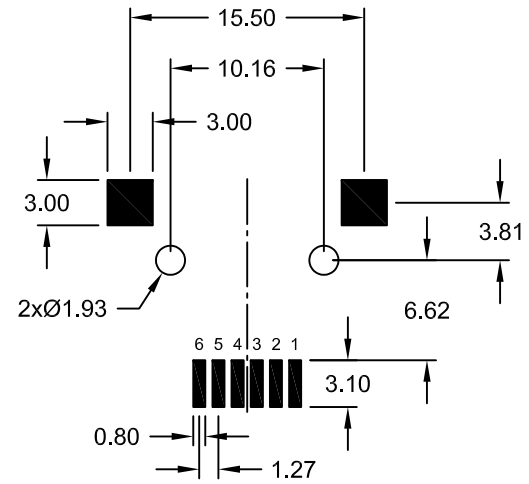
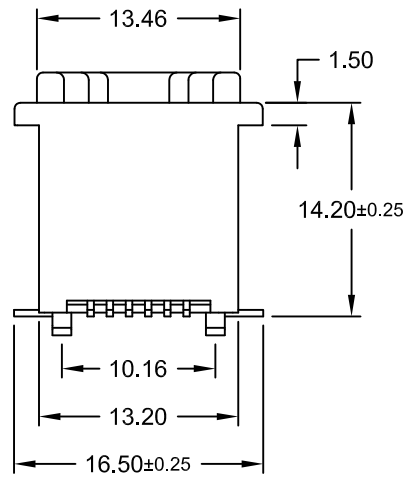
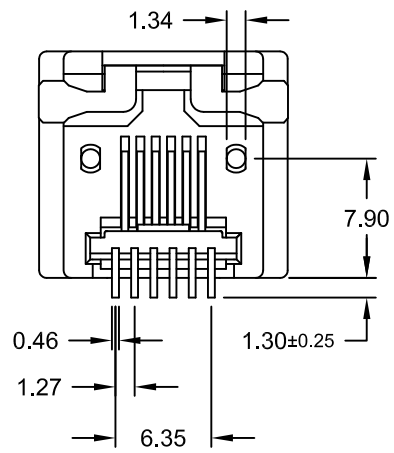
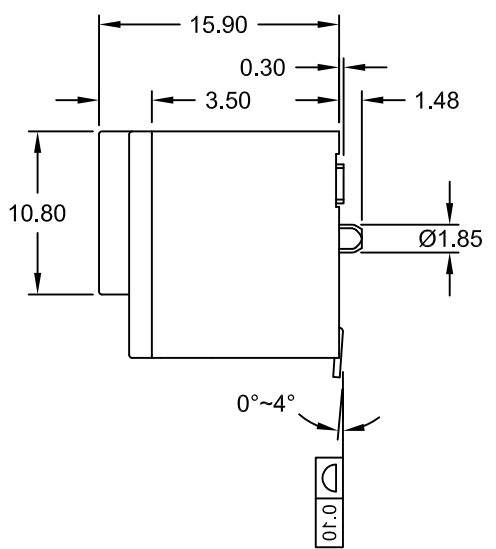
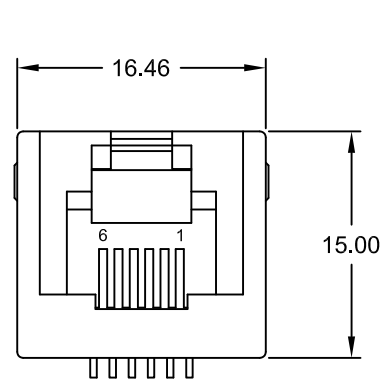
Material

Contact: Phosphor Bronze t=0.35mm
 Plating: Au on solder area;
 Au on contact area (see PN code)
 Insulator: PA9T GN2330 (black) UL 94V-0
 Insert Insulator: Stanyl TE250F6 (Black) UL 94V-0

Operating temperature: -20°C to +85°C
 Processing temperature: +250°C +0/-5°C
 for 10 seconds

Cavity comply with FCC Rules and Regulations
 Part 68, Subpart F

Packing: 350 pcs./reel



Recommended PCB Layout
(Top View)

PART NUMBER	GOLD PLATING CONTACT AREA
MJT-166-W3S0-55/R	flash
MJT-166-W3S0-56/R	6µ"

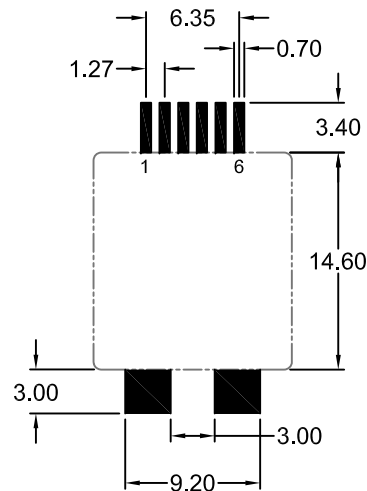
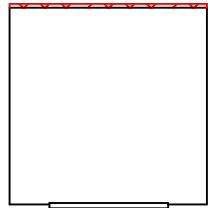
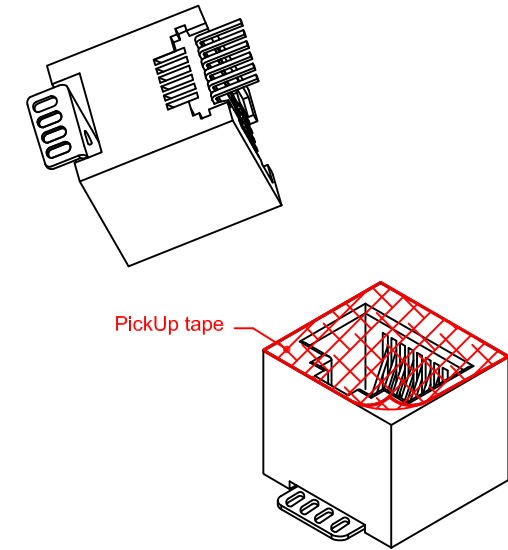
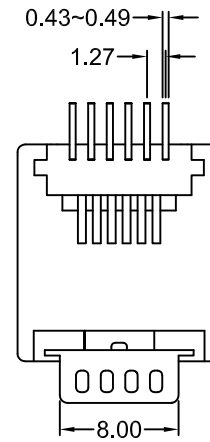
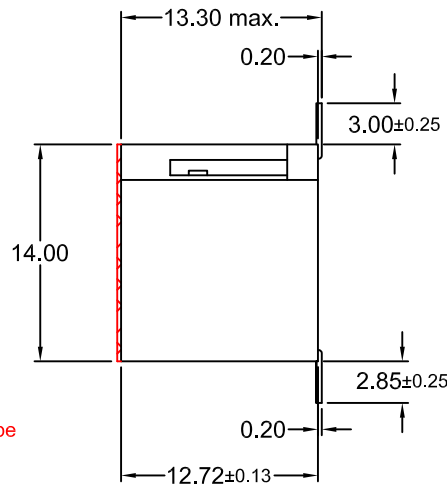
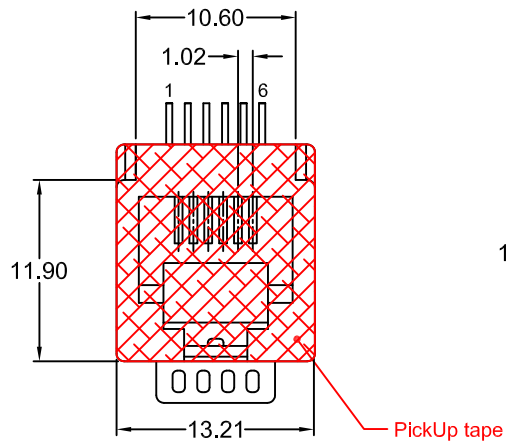
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UNIT	SCALE	GENERAL TOLERANCE	DRAWN	DATE	DWG. NO.	SHEET 1/1
mm	Free	X.° ± X. ±	RH	13.08.2001	1811301	REV. F
		.X° ± .X ±	CHECK	01.07.2016	SERIES NO.	
		.XX° ± .XX ± 0.13	APPROVE	01.07.2016	MJT-166-W3S0-xx/R	
		.XXX° ± .XXX ±	Hogi			

Top Entry SMT PCB Jack
RJ12 <6P6C> NON shielded
with panel stop

REV.	DESCRIPTION	DATE	DRAWN
A	NEW	11.02.2014	Ryan Chou



Recommended PCB Hole Layout
(Top View)

Specifications

Current rating: 1.5A
 Insulation resistance: 500MΩ min.
 Withstanding voltage: 1000V rms 60Hz / Minute
 Contact resistance: 50mΩ max.
 Operating temperature: -40°C to +85°C



Materials

Contact: Phosphor Bronze (t=0.35mm)
 Plating: Au in solder area; Au in contact area
 Insulator: Nylon 9T UL 94V-0 (Black)
 Insert Insulator: Nylon 46 UL 94V-0 (Black)

Cavity conforms to FCC Rules and Registration PAR68,
 Subparts F

Packing

Reel

PART NUMBER	GOLD PLATING CONTACT AREA
MJT-166-T3S0-55/R	3μ"
MJT-166-T3S0-56/R	6μ"
MJT-166-T3S0-57/R	15μ"
MJT-166-T3S0-58/R	30μ"
MJT-166-T3S0-5H/R	50μ"



UNIT	mm
SCALE	Free

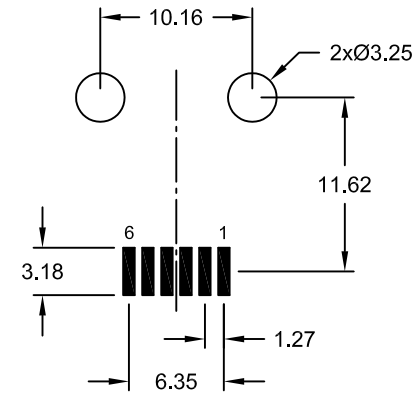
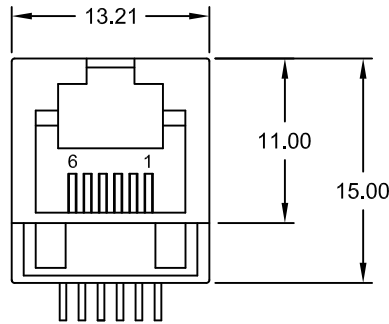
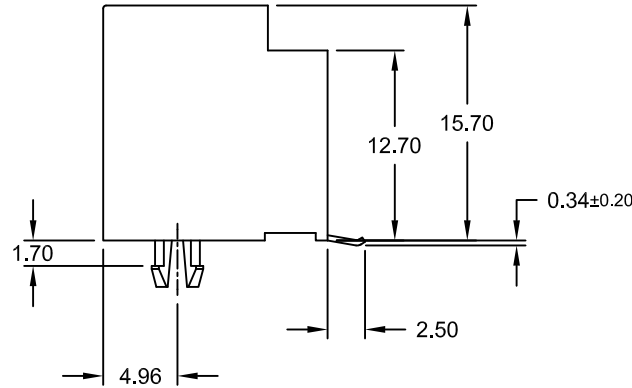
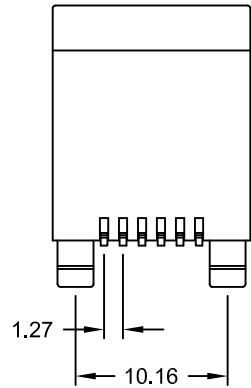
GENERAL TOLERANCE	
X.° ±	.X° ±
X. ±	.X ±0.25
XX. ±	.XX ±0.15
XXX. ±	.XXX ±0.075

DRAWN	DATE
Ryan Chou	11.02.2014
CHECK	DATE
Ronny	11.02.2014
APPROVE	DATE
Hogi	11.02.2014

DWG. NO.	SHEET 1/1
1811302	REV. A
Series NO.	
MJT-166-T3S0-xx/X	

SMT PCB Jack RJ12 <6P6C>
 Top Entry
 NON shielded

REV.	DESCRIPTION	DATE	DRAWN
A	NEW	16.11.2015	Cherry



Recommended PCB Layout Top View
(Tolerance ±0.05)



Specifications

Electrical

Current rating: 1.5A
 Insulation resistance: 500MΩ min. @ 500V DC
 Voltage rating: 125V AC rms
 Withstanding voltage: 1000V AC rms 50Hz / Minute
 Contact resistance: 50mΩ max.

Material

Contact: Phosphor Bronze
 Plating: Sn on solder area,
 Au on contact area;
 entire contact Ni underplated
 Insulator: Nylon 6T (Black) UL 94V-0

Operating temperature: -40°C to +85°C
 Processing temperature: 250°C +0/-5°C
 for 10 seconds

Mechanical Requirements

Operating Life: 750 cycles min.

Packing

Tray (standard) or Reel

Cavity comply with FCC Rules and
 Regulations Part 68, Subpart F

Packing

standard Tray (no suffix)
 /R = Reel with PickUp Tape

PART NUMBER	GOLD PLATING CONTACT AREA
MJT-166-T1S1-96/X	6μ"
MJT-166-T1S1-97/X	15μ"
MJT-166-T1S1-98/X	30μ"
MJT-166-T1S1-9H/X	50μ"

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UNIT mm	GENERAL TOLERANCE		DRAWN Cherry	DATE 16.11.2015	DWG. NO. 1811303	SHEET 1/1
	X.° ±	X. ±				CHECK Ronny
	.XX° ±	.XX ± 0.25	APPROVE Hogi	DATE 16.11.2015		
	.XXX° ±	.XXX ±				

Top Entry SMT PCB Jack
 RJ12 <6P6C>
 NON shielded